

ABSTRACT

An adhesive film (100) including a base material layer (A),
an adhesive resin layer (B) for temporarily fixing an electronic
5 component on a first surface (A1) side of the base material
layer (A), and an adhesive resin layer (C) on a second surface
(A2) side of the base material layer (A), in which an arithmetic
average height S_a of a surface of the adhesive resin layer (C)
opposite to the base material layer (A) is $5.5\ \mu\text{m}$ or more, in a
10 case where a test piece having a size of 5 cm x 5 cm is produced
from the adhesive film (100), and the test piece is subjected to
a pressurization and heating treatment for 1 minute under
conditions of a temperature of 190°C , a load of 100 kN, and a
humidity of 65% Rh in a state of being interposed between two
15 SUS plates having a size of 15 cm x 15 cm.